

2017 IEEE 21st Workshop on Signal and Power Integrity (SPI 2017)

**Lake Maggiore (Baveno), Italy
7 – 10 May 2017**



**IEEE Catalog Number: CFP17SPI-POD
ISBN: 978-1-5090-5617-0**

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IEEE Catalog Number:	CFP17SPI-POD
ISBN (Print-On-Demand):	978-1-5090-5617-0
ISBN (Online):	978-1-5090-5616-3

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